Special Issue

Research on Green and Environmentally Friendly Lead-Free Solder and Advanced Interconnect Technology in Electronic Packaging

Message from the Guest Editor

In the process of connecting microelectronics, the industry not only needs to prohibit the doping of harmful elements from the source, but also ensure the reliability of the connection. This requires researchers to propose new strategies in terms of connection technology, materials and structural design. Since the end of the 1990s, many researchers have attempted to improve the reliability of tin-based solder and to regulate the properties of intermetallic compounds to weaken the brittle tendency of solder joints, whether they are from the solder itself, the interface coating or external conditions. In addition, the reuse of solid waste resources of electronic products is also a new theme of green connection, and the design of electronic products should also consider the convenience of recycling. Methods of recovering valuable rare elements from electronic products is also an important issue.

Guest Editor

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Metallic materials play a vital role in the economic life of modern societies; contributions are sought on fresh developments that enhance our understanding of the fundamental aspects related to the relationships between processing, properties and microstructure – disciplines in the metallurgical field ranging from processing, mechanical behavior, phase transitions and microstructural evolution, nanostructures, as well as unique metallic properties – inspire general and scholarly interest among the scientific community.

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